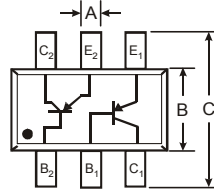


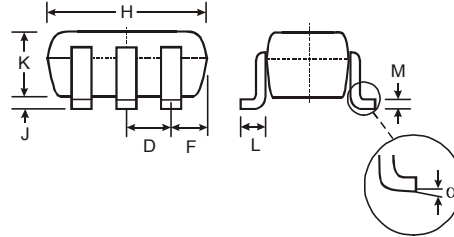
**Features**

- Epitaxial Planar Die Construction
- Intrinsically Matched PNP Pair (Note 1)
- Small Surface Mount Package
- 2% Matched Tolerance,  $h_{FE}$ ,  $V_{CE(SAT)}$ ,  $V_{BE(SAT)}$
- **Lead Free/RoHS Compliant (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- "Green" Device (Note 4 and 5)



**Mechanical Data**

- Case: SOT-363
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Terminal Connections: See Diagram
- Marking Information: K4B, See Page 4
- Ordering & Date Code Information: See Page 4
- Weight: 0.015 grams (approximate)



SOT-363		
Dim	Min	Max
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Nominal	
F	0.30	0.40
H	1.80	2.20
J	—	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.25
$\alpha$	0°	8°
All Dimensions in mm		

**Maximum Ratings** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	-40	V
Collector-Emitter Voltage	$V_{CEO}$	-40	V
Emitter-Base Voltage	$V_{EBO}$	-5.0	V
Collector Current - Continuous	$I_C$	-200	mA
Power Dissipation (Note 3)	$P_d$	200	mW
Thermal Resistance, Junction to Ambient (Note 3)	$R_{\theta JA}$	625	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	$T_j, T_{STG}$	-55 to +150	$^\circ\text{C}$

- Notes:
1. Built with adjacent die from a single wafer.
  2. No purposefully added lead.
  3. Device mounted on FR5 PCB: 1.0 x 0.75 x 0.62 in.; pad layout as shown on suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  4. Diodes Inc.'s "Green" policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  5. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

## Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition	
<b>OFF CHARACTERISTICS (Note 6)</b>						
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	-40	—	V	I <sub>C</sub> = -10μA, I <sub>E</sub> = 0	
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	-40	—	V	I <sub>C</sub> = -1.0mA, I <sub>B</sub> = 0	
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	-5.0	—	V	I <sub>E</sub> = -10μA, I <sub>C</sub> = 0	
Collector Cutoff Current	I <sub>CEX</sub>	—	-50	nA	V <sub>CE</sub> = -30V, V <sub>EB(OFF)</sub> = -3.0V	
Base Cutoff Current	I <sub>BL</sub>	—	-50	nA	V <sub>CE</sub> = -30V, V <sub>EB(OFF)</sub> = -3.0V	
<b>ON CHARACTERISTICS (Note 6)</b>						
DC Current Gain	(Note 7)	h <sub>FE</sub>	60	—	—	I <sub>C</sub> = -100μA, V <sub>CE</sub> = -1.0V
			80	—		I <sub>C</sub> = -1.0mA, V <sub>CE</sub> = -1.0V
			100	300		I <sub>C</sub> = -10mA, V <sub>CE</sub> = -1.0V
			60	—		I <sub>C</sub> = -50mA, V <sub>CE</sub> = -1.0V
			30	—		I <sub>C</sub> = -100mA, V <sub>CE</sub> = -1.0V
Collector-Emitter Saturation Voltage	(Note 7)	V <sub>CE(SAT)</sub>	—	-0.25 -0.40	V	I <sub>C</sub> = -10mA, I <sub>B</sub> = -1.0mA I <sub>C</sub> = -50mA, I <sub>B</sub> = -5.0mA
Base-Emitter Saturation Voltage	(Note 7)	V <sub>BE(SAT)</sub>	-0.65	-0.85 -0.95	V	I <sub>C</sub> = -10mA, I <sub>B</sub> = -1.0mA I <sub>C</sub> = -50mA, I <sub>B</sub> = -5.0mA
Base-Emitter Voltage Matching		ΔV <sub>BE</sub>	—	-1	mV	V <sub>CE</sub> = -5V, I <sub>C</sub> = -2mA
<b>SMALL SIGNAL CHARACTERISTICS</b>						
Output Capacitance	C <sub>obo</sub>	—	4.5	pF	V <sub>CB</sub> = -5.0V, f = 1.0MHz, I <sub>E</sub> = 0	
Input Capacitance	C <sub>ibo</sub>	—	10	pF	V <sub>EB</sub> = -0.5V, f = 1.0MHz, I <sub>C</sub> = 0	
Input Impedance	h <sub>ie</sub>	2.0	12	kΩ	V <sub>CE</sub> = 10V, I <sub>C</sub> = 1.0mA, f = 1.0kHz	
Voltage Feedback Ratio	h <sub>re</sub>	0.1	10	x 10 <sup>-4</sup>		
Small Signal Current Gain	h <sub>fe</sub>	100	400	—		
Output Admittance	h <sub>oe</sub>	3.0	60	μS		
Current Gain-Bandwidth Product	f <sub>T</sub>	250	—	MHz		V <sub>CE</sub> = -20V, I <sub>C</sub> = -10mA, f = 100MHz
Noise Figure	NF	—	4.0	dB	V <sub>CE</sub> = -5.0V, I <sub>C</sub> = -100μA, R <sub>S</sub> = 1.0kΩ, f = 1.0kHz	
<b>SWITCHING CHARACTERISTICS</b>						
Delay Time	t <sub>d</sub>	—	35	ns	V <sub>CC</sub> = -3.0V, I <sub>C</sub> = -10mA,	
Rise Time	t <sub>r</sub>	—	35	ns	V <sub>BE(off)</sub> = 0.5V, I <sub>B1</sub> = -1.0mA	
Storage Time	t <sub>s</sub>	—	225	ns	V <sub>CC</sub> = -3.0V, I <sub>C</sub> = -10mA,	
Fall Time	t <sub>f</sub>	—	75	ns	I <sub>B1</sub> = I <sub>B2</sub> = -1.0mA	

- Notes: 6. Short duration pulse test used to minimize self-heating effect.  
7. The DC current gain, h<sub>FE</sub>, (matched at I<sub>C</sub> = -10mA and V<sub>CE</sub> = -1.0V) Collector Emitter Saturation Voltage, V<sub>CE(SAT)</sub>, and Base Emitter Saturation Voltage, V<sub>BE(SAT)</sub> are matched with typical matched tolerances of 1% and maximum of 2%.

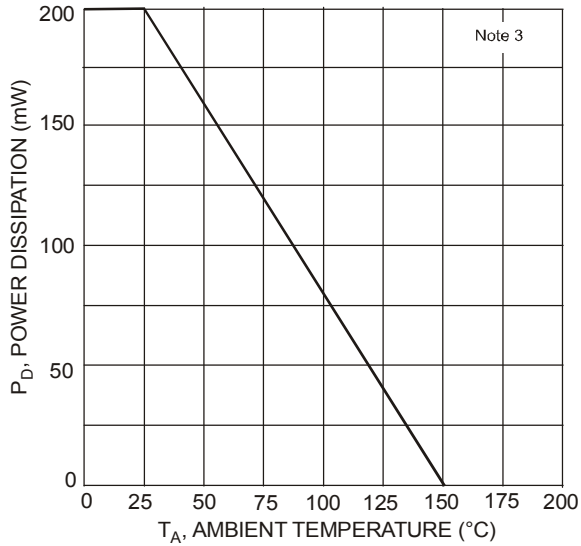


Fig. 1, Max Power Dissipation vs. Ambient Temperature

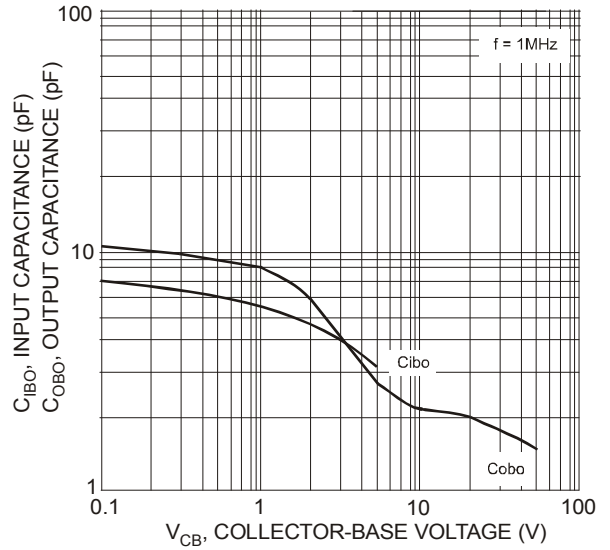


Fig. 2, Input and Output Capacitance vs. Collector-Base Voltage

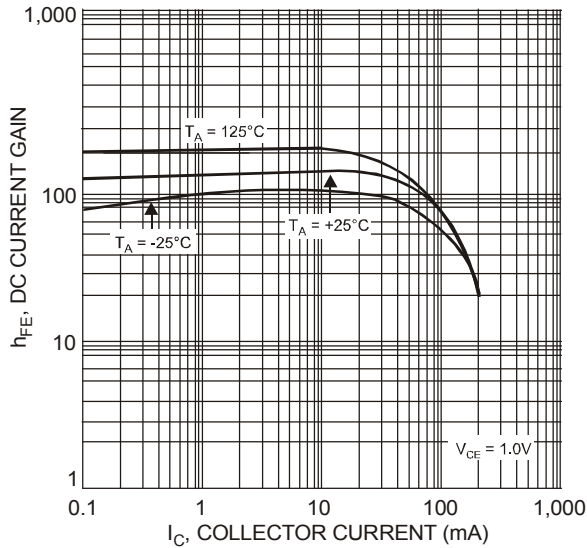


Fig. 3, Typical DC Current Gain vs. Collector Current

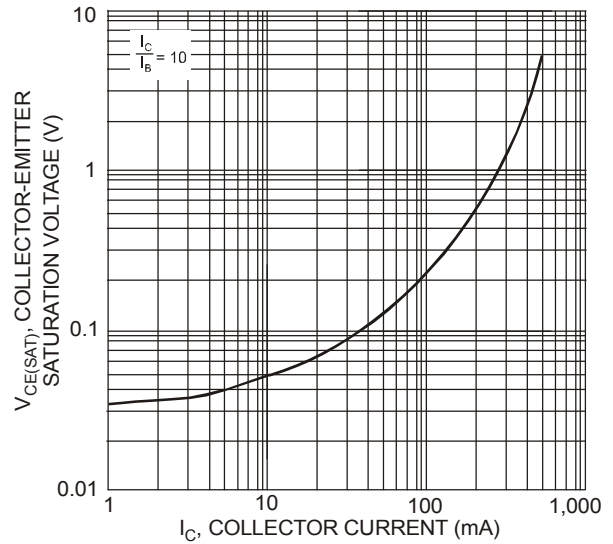


Fig. 4, Typical Collector-Emitter Saturation Voltage vs. Collector Current

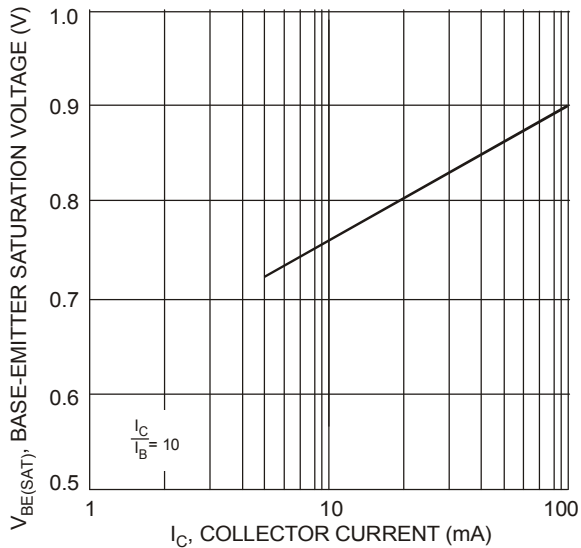


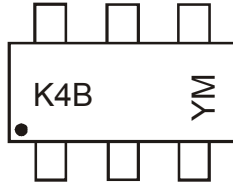
Fig. 5, Typical Base-Emitter Saturation Voltage vs. Collector Current

## Ordering Information (Note 8)

Device	Packaging	Shipping
DMMT3906W-7-F	SOT-363	3000/Tape & Reel

Notes: 8. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

## Marking Information



K4B = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year ex: T = 2006  
 M = Month ex: 9 = September

### Date Code Key

Year	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	N	P	R	S	T	U	V	W	X	Y	Z

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

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- Поставка более 17-ти миллионов наименований электронных компонентов;
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- Экспресс доставка в любую точку России;
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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

**Телефон:** 8 (812) 309 58 32 (многоканальный)

**Факс:** 8 (812) 320-02-42

**Электронная почта:** [org@eplast1.ru](mailto:org@eplast1.ru)

**Адрес:** 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.